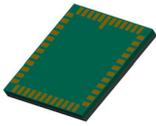
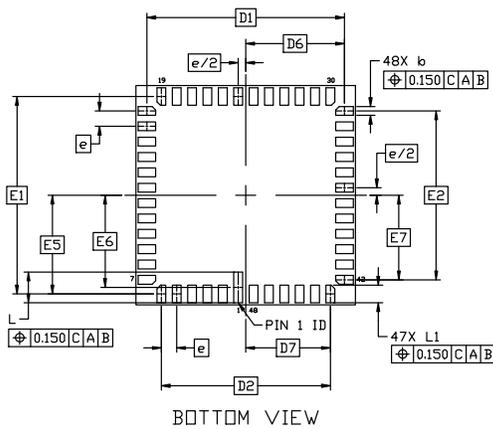
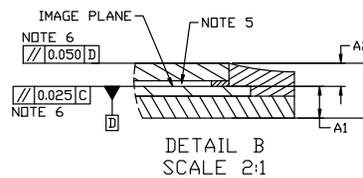
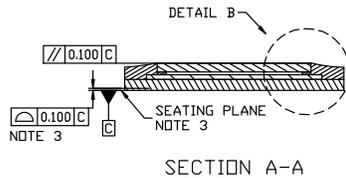
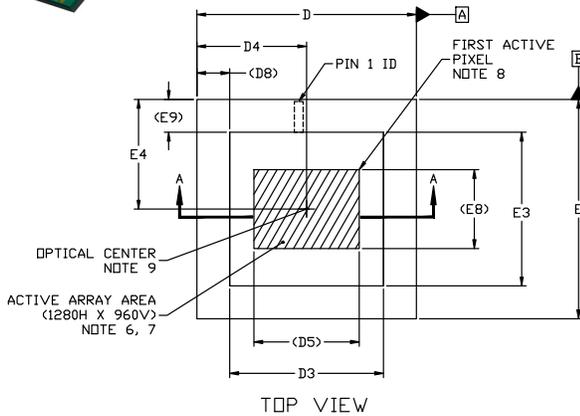


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

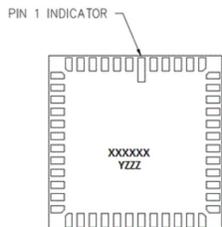


ILCC48 10.00x10.00x1.25, 0.70P CASE 847AE ISSUE A

DATE 30 JUN 2023



GENERIC MARKING DIAGRAM*



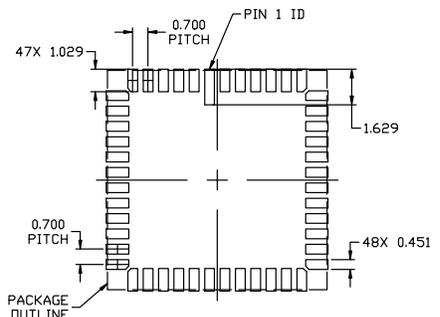
XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER [mm].
3. COPLANARITY APPLIES TO THE PLATED LAND PADS.
4. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
5. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
6. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
7. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±1°.
8. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
9. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.00096, -0.002).
10. PACKAGE CENTER (X, Y) = (0.000, 0.000).

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	1.375
A1	0.650	0.725	0.800
A2	0.475	0.525	0.575
b	0.350	0.400	0.450
D	9.925	10.000	10.075
D1	9.000 BSC		
D2	7.700 BSC		
D3	6.900	7.000	7.100
D4	4.925	5.000	5.075
D5	4.800 REF.		
D6	4.500 BSC		
D7	3.850 BSC		
D8	1.500 REF.		
E	9.925	10.000	10.075
E1	9.000 BSC		
E2	7.700 BSC		
E3	6.900	7.000	7.100
E4	4.925	5.000	5.075
E5	4.500 BSC		
E6	4.200 BSC		
E7	3.85 BSC		
E8	3.600 REF.		
E9	1.500 REF.		
e	0.700 BSC		
L	1.350	1.400	1.450
L1	0.750	0.800	0.850



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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DESCRIPTION:	ILCC48 10.00x10.00x1.25, 0.70P	PAGE 1 OF 1

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